

Absolute Maximum Ratings at $T_J=25$ (unless otherwise specified)
 Parameter Conditions

Value Unit

Absolute Maximum Ratings
 Parameter

Symbol

Max

Unit

Electrical Characteristics at $T_J=25$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	150	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2	3	4	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V, V_{DS}=150V, T_J=25$	-	-	1	μA
		$V_{GS}=0V, V_{DS}=150V, T_J=100$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=20A$	-	9.6	11.5	m Ω
Transconductance	g_{fs}	$V_{DS}=5V, I_D=20A$	-	65	-	S
Gate Resistance	R_G	$V_{GS}=0V, V_{DS}$ Open, $f=1MHz$	-	2.8	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=75V, f=1MHz$	-	3365	-	pF
Output Capacitance	C_{oss}		-	239	-	
Reverse Transfer Capacitance	C_{rss}		-	6.5	-	
Total Gate Charge	$Q_g(10V)$	$V_{DD}=75V, I_D=20A, V_{GS}=10V$	-	42	-	nC
Gate to Source Charge	Q_{gs}		-	14	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	7	-	
Turn on Delay Time	$t_{d(on)}$	$V_{DD}=75V, I_D=20A, V_{GS}=10V, R_G=10\Omega,$	-	17	-	ns
Rise time	t_r		-	8	-	
Turn off Delay Time	$t_{d(off)}$		-	26	-	
Fall Time	t_f		-	10	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_F=20A$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=75V, I_F=20A, di_F/dt=100A/\mu s$	-	80	-	ns
Reverse Recovery Charge	Q_{rr}		-	160	-	nC



Fig 1. Typical Output Characteristics

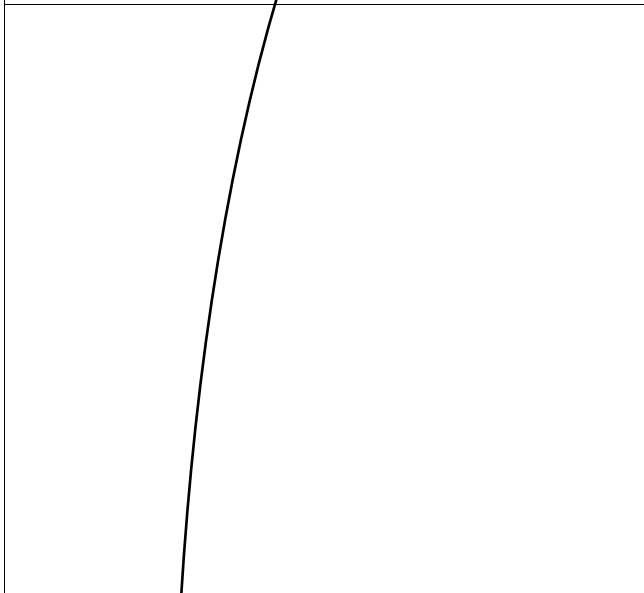


Figure 2. On-Resistance vs. Gate-Source Voltage

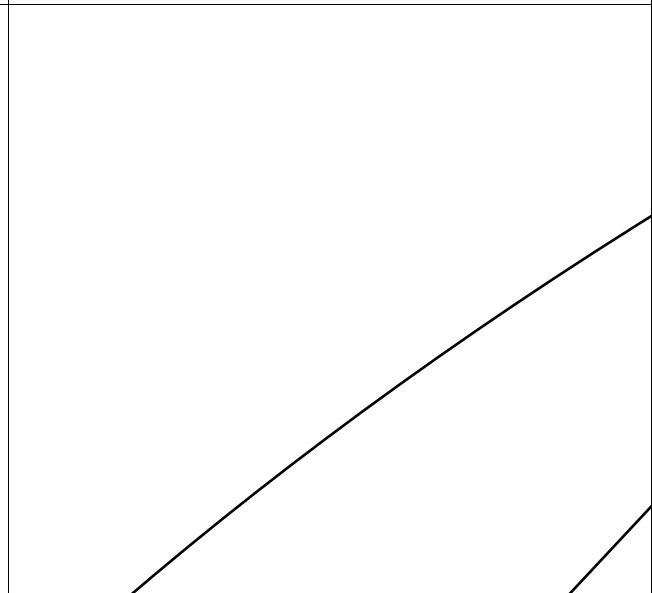


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

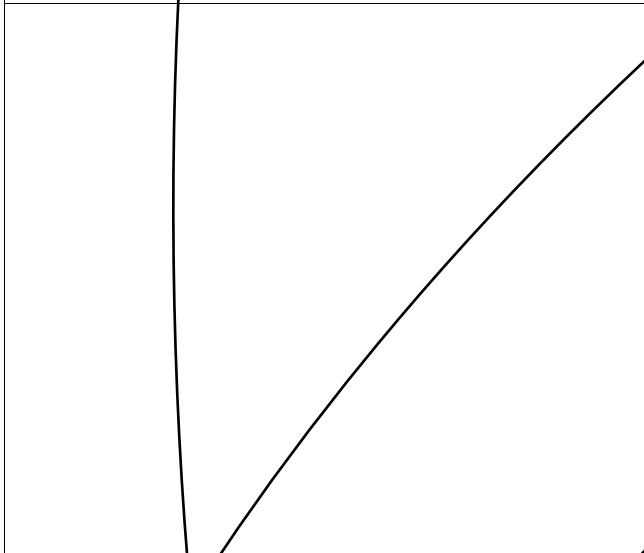


Figure 4. Normalized On-Resistance vs. Junction Temperature

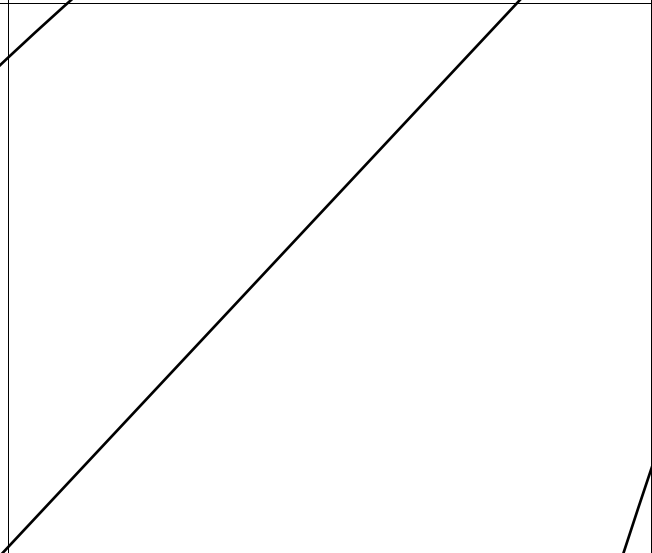


Figure 5. Typical Transfer Characteristics

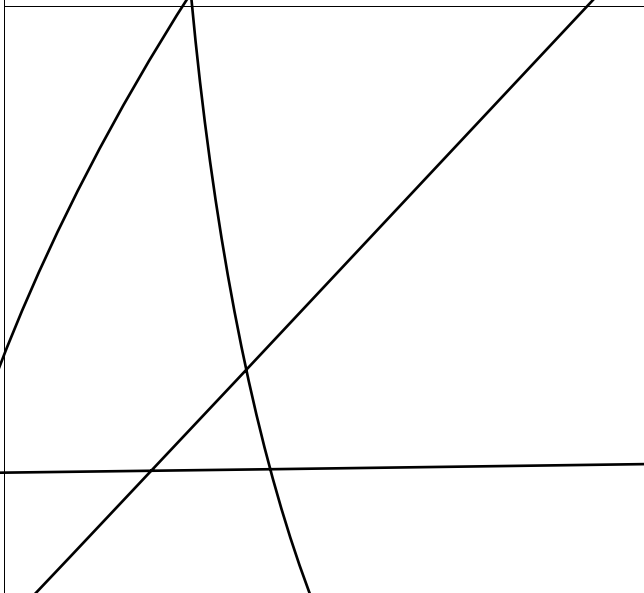


Figure 6. Typical Source-Drain Diode Forward Voltage

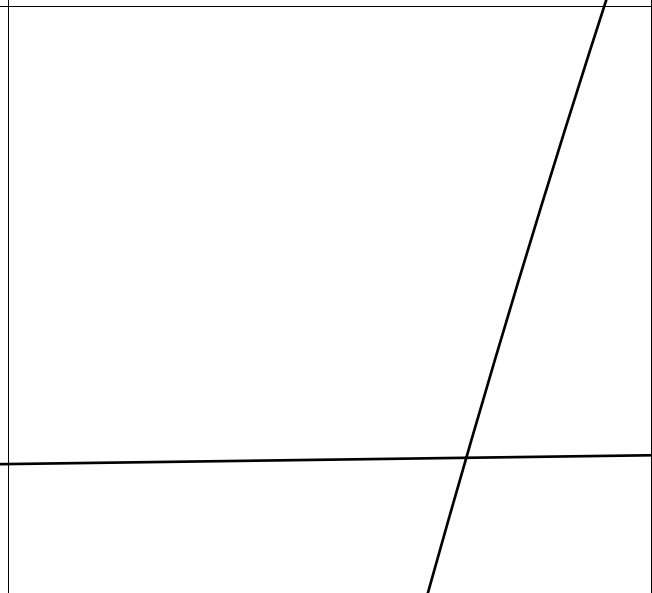


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

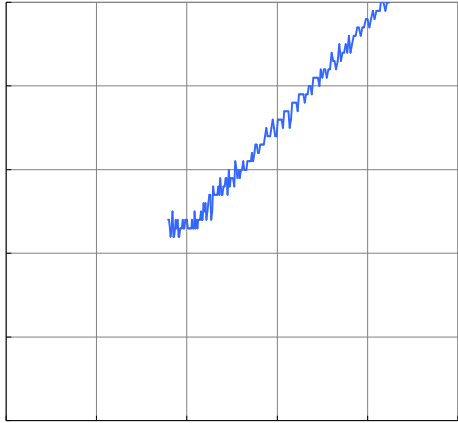


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

Figure 9. Maximum Safe Operating Area

Figure 10. Maximun Drain Current vs. Case Temperature

Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient

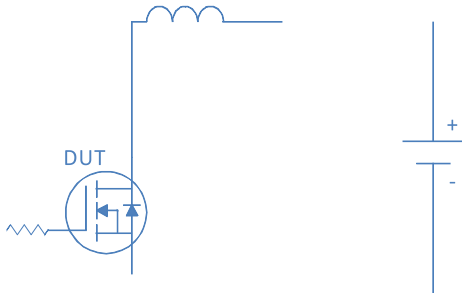
Inductive switching Test

--	--

Gate Charge Test

--	--

Uclamped Inductive Switching (UIS) Test

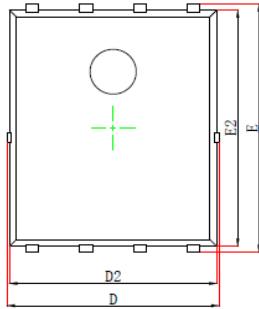
 <p>The diagram illustrates the UIS test setup. A MOSFET, labeled 'DUT', is connected in series with an inductor. The MOSFET's gate is driven by a pulse source (represented by a resistor and a pulse). The MOSFET's drain is connected to one terminal of the inductor, and the other terminal of the inductor is connected to the positive terminal of a DC voltage source. The negative terminal of the DC source is connected to the MOSFET's source and the cathode of a diode. The diode's anode is connected to the MOSFET's drain, forming a flyback diode path.</p>	
--	--

Diode Recovery Test

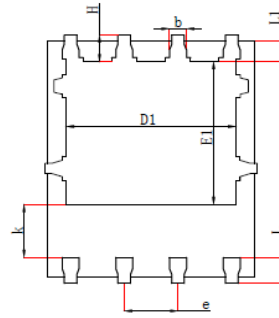
--	--

Package Outline

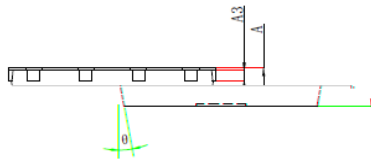
DFN5x6_P, 8 Leads



Top View
[顶视图]



Bottom View
[背视图]



Side View
[侧视图]

Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	0.900	1.100	0.035	0.043	
A3	0.254 REF		0.010 REF		
D	4.680	5.120	0.184	0.202	
E	5.000	5.426	0.394	0.214	
3.610	4.110	0.142	0.162	D1	
3.380	3.780	0.133	0.149	L1	
4.800	5.000	0.189	0.197	D2	
5.074	5.826	0.223	0.229	L2	
1.100	1.390	0.043	0.055	k	
0.330	0.510	0.013	0.020	b	
	1.2/0TYP		1.2/0TYP	e	
0.510	0.711	0.020	0.028	L	
0.017	0.023		L1	0.424	
0.026	0.016		0.029	L H	
				0.410	
theta	0°	12°	0°	12°	